

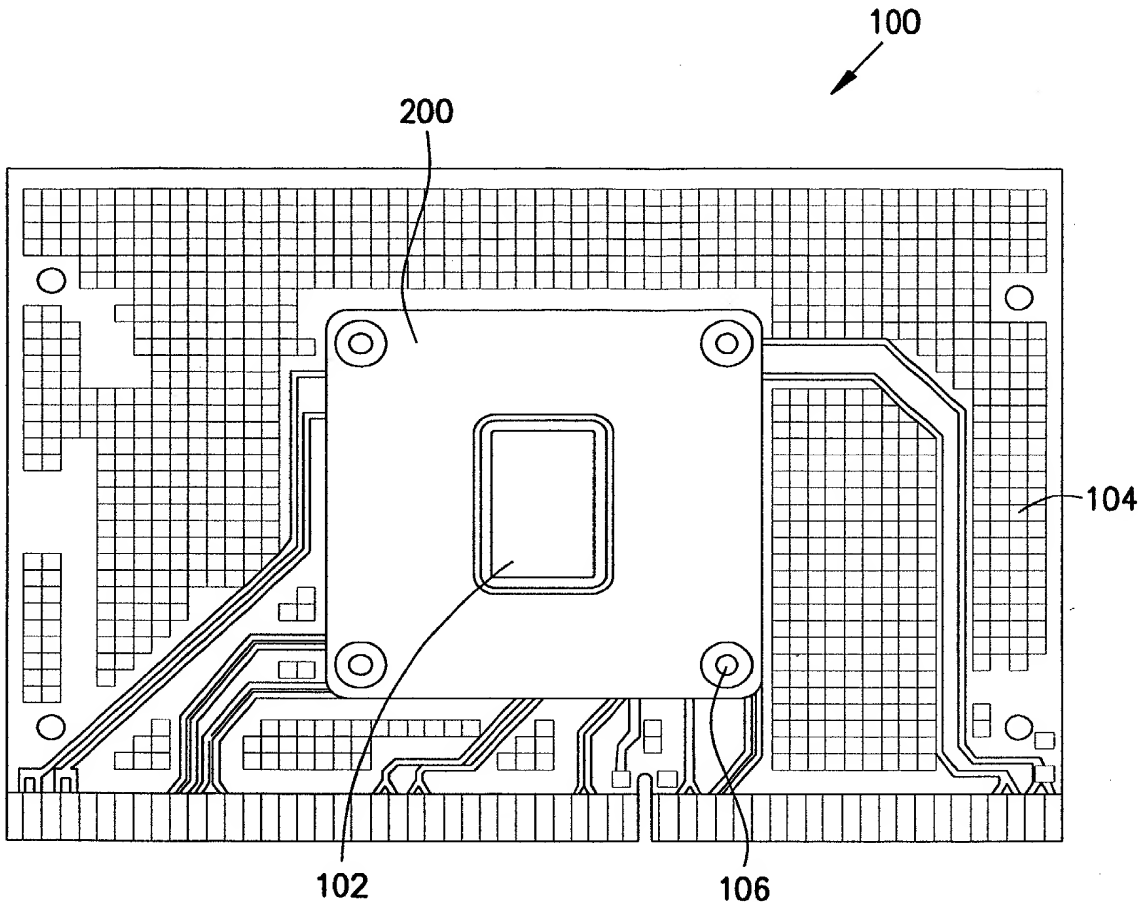
[illegible]

FIG. 1

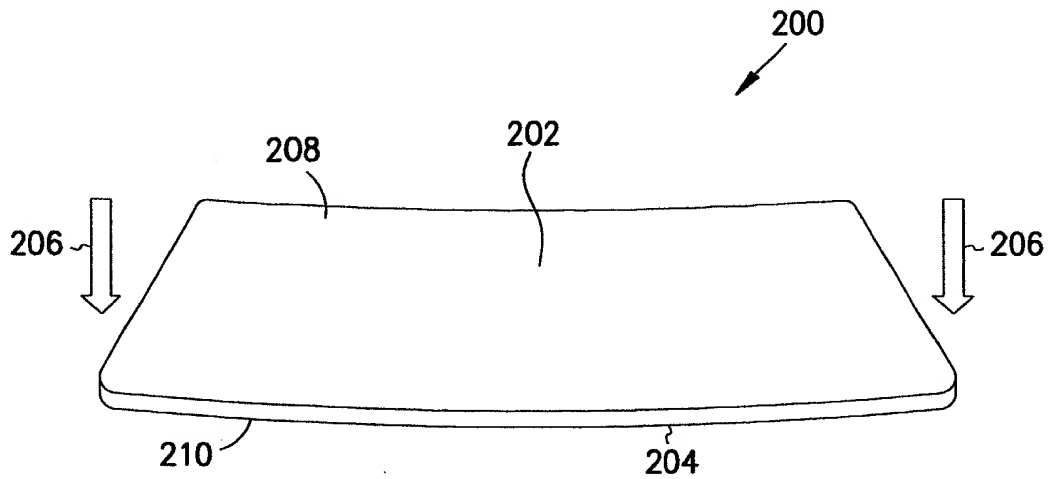


FIG. 2

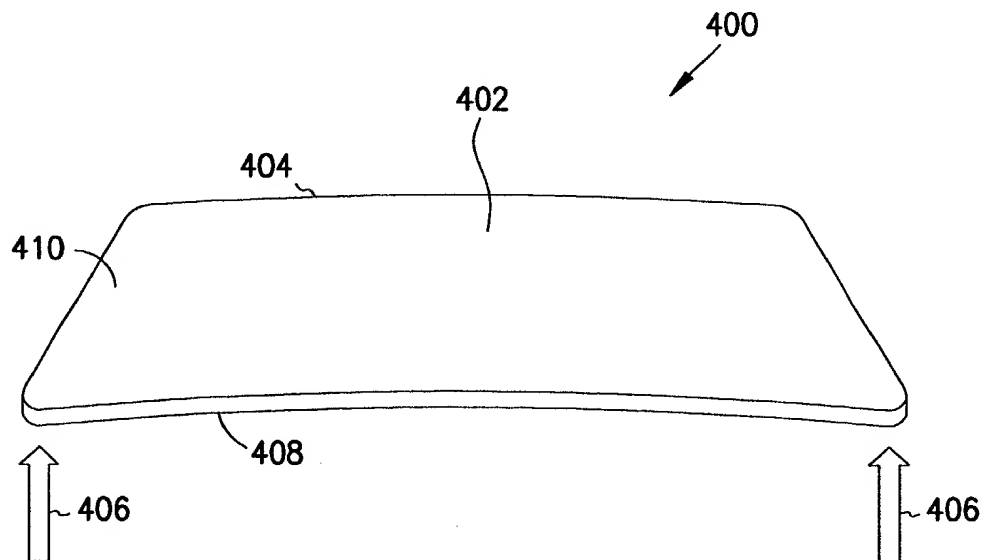


FIG. 4

Sheet 3 of 6

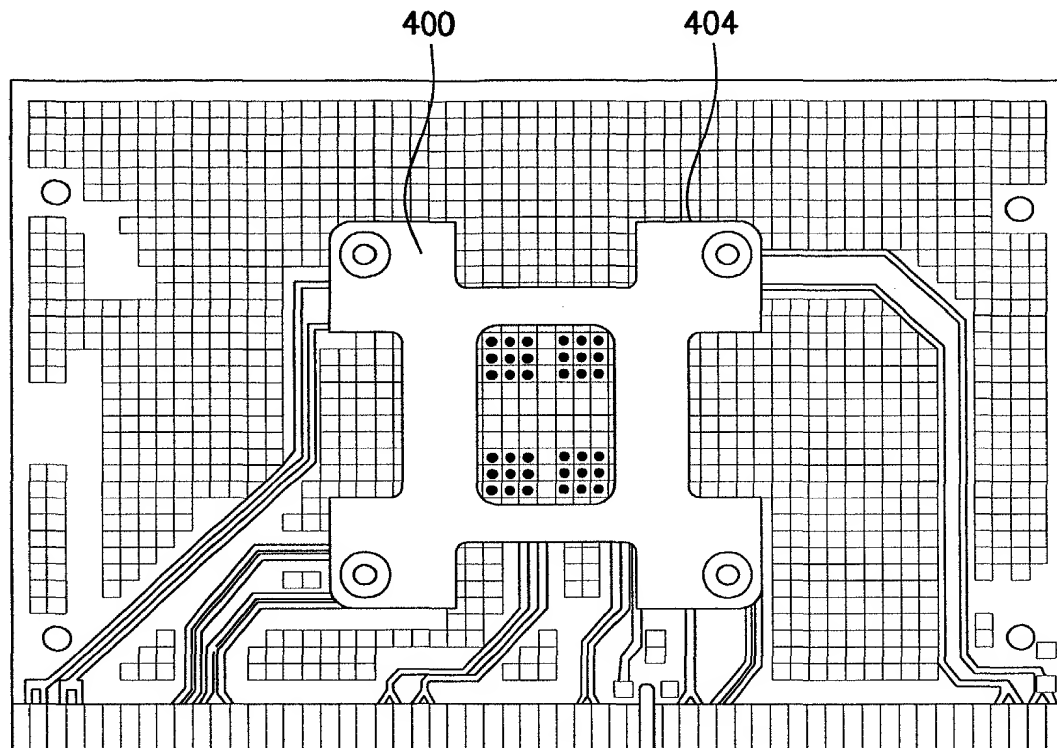


FIG. 3

This diagram shows an exploded perspective view of a multi-layered assembly, designated by the numeral 6. The assembly consists of several components aligned vertically. At the top is a square plate 200 with a central square opening. It is secured by four screws 106, each passing through a hole in the plate and a corresponding hole in a larger rectangular plate 104 below it. Below plate 200 is a rectangular ring 500. Underneath the ring is a square plate 102 with a central rectangular protrusion. Below plate 102 is another square plate 504. At the bottom is a larger rectangular plate 104. A smaller square plate 400 is positioned below plate 104, with four screws 106 passing through it and into plate 104. The screws 106 are shown in an exploded state, indicating they are used to secure the assembly.

FIG. 5

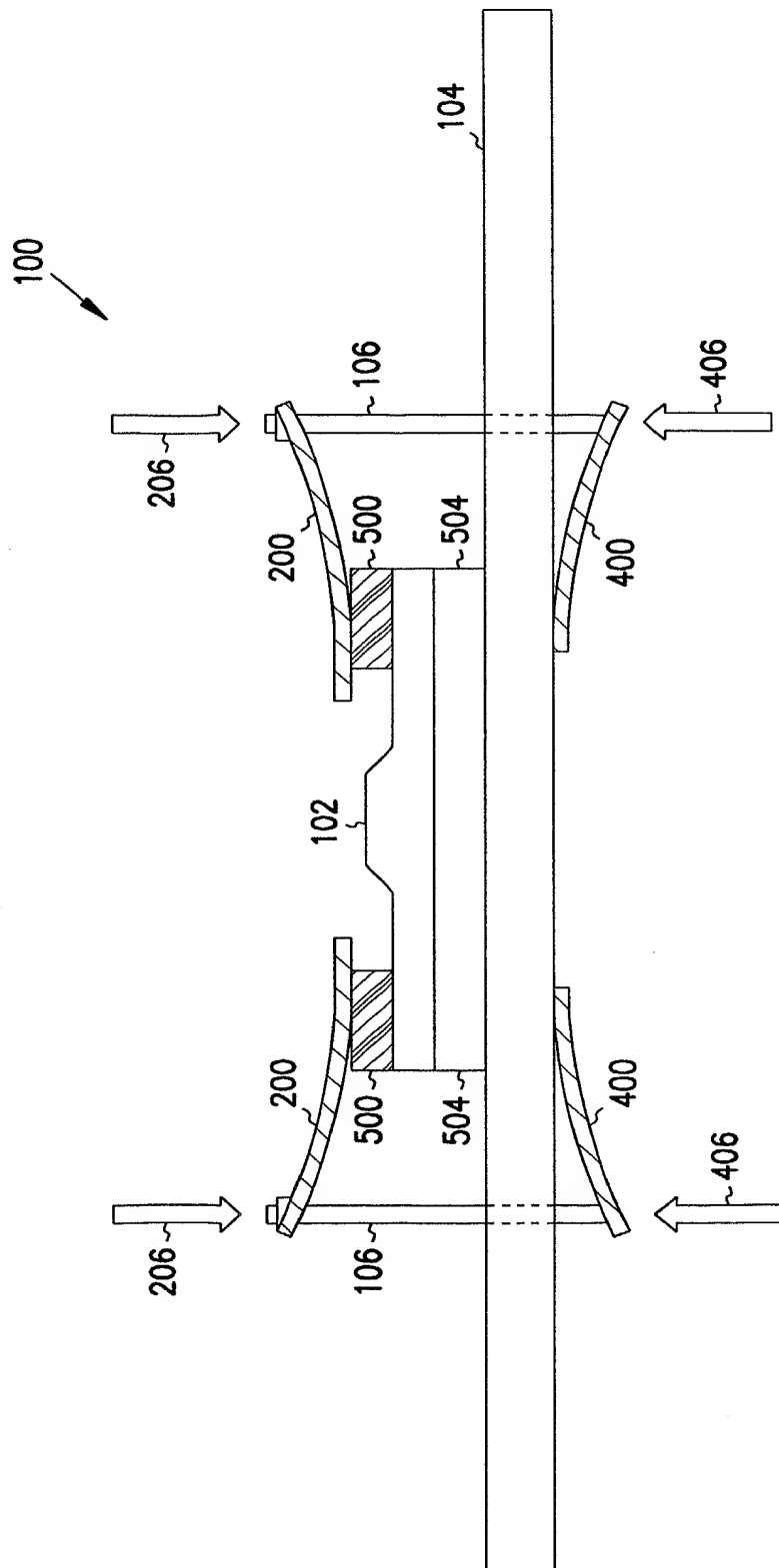
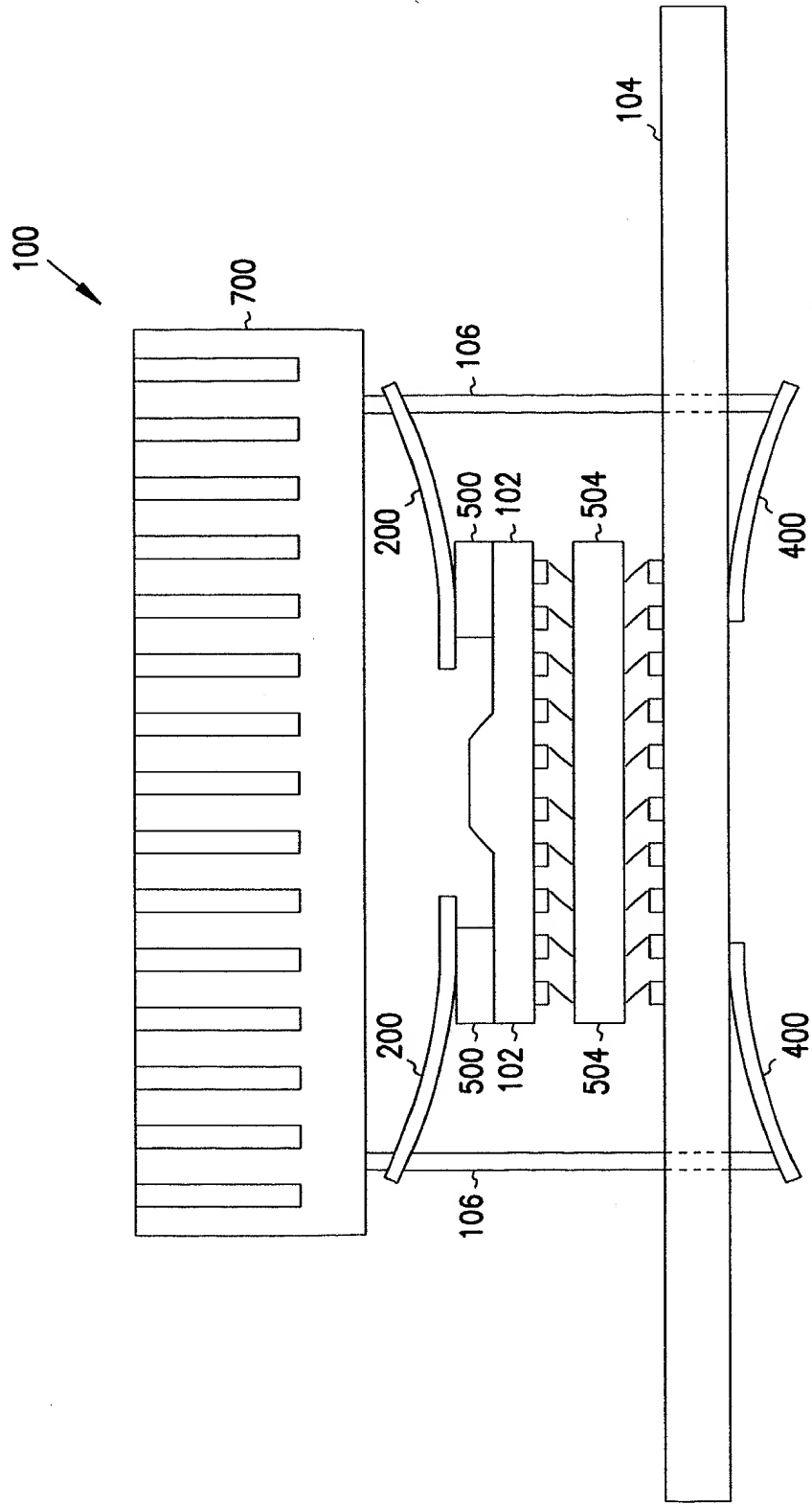


FIG. 6



**FIG. 7**

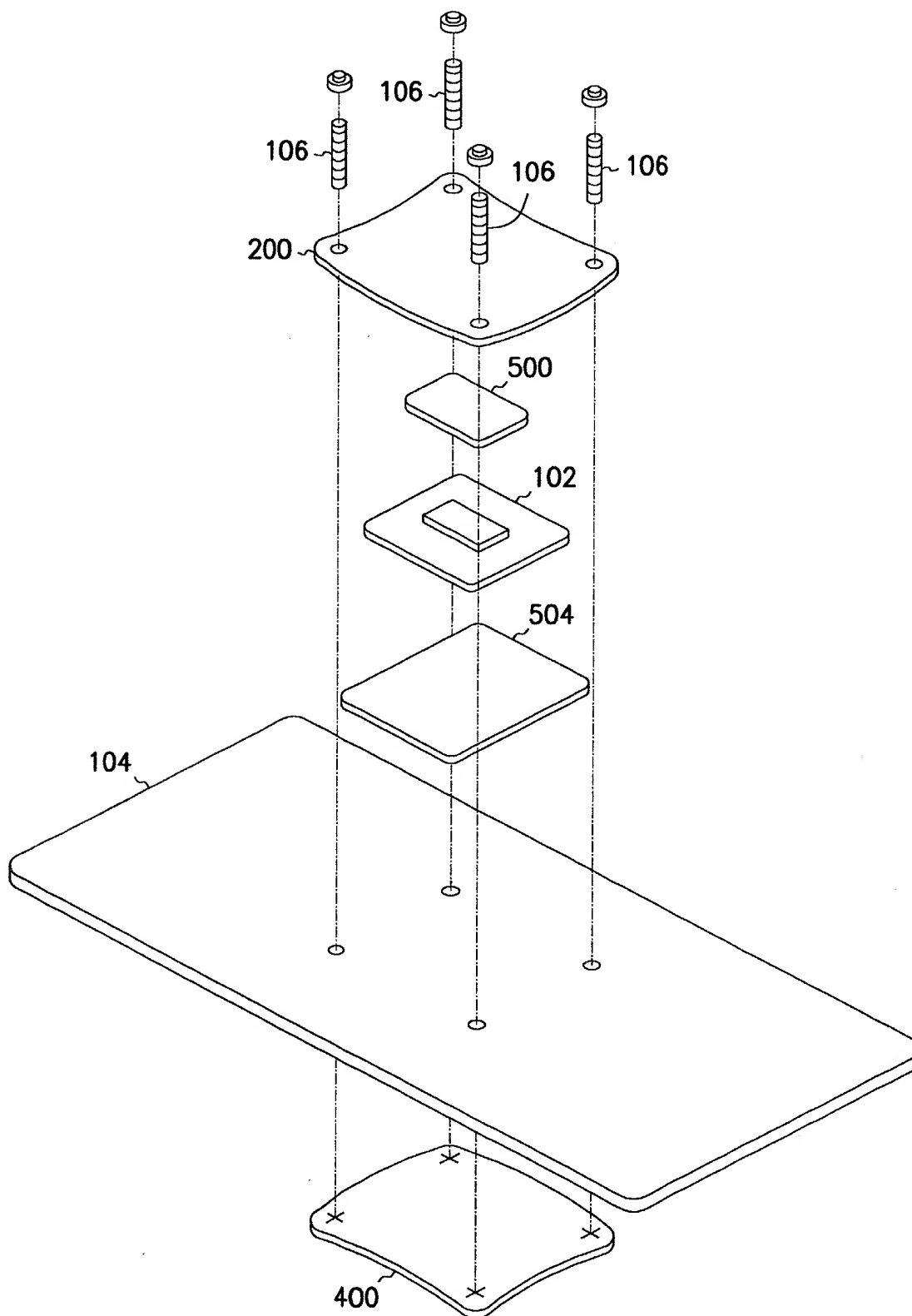


FIG. 8

0973476 40000

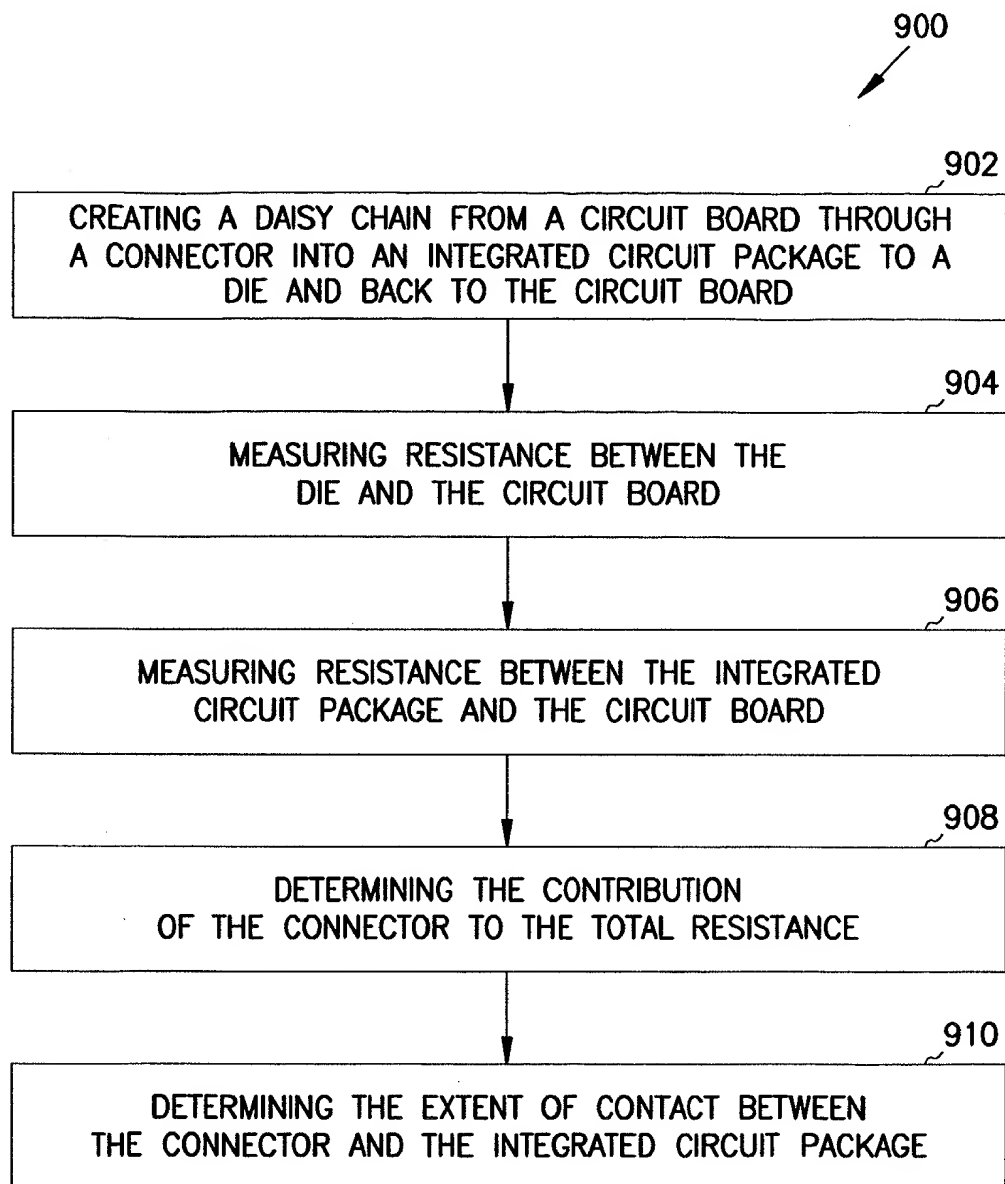


FIG. 9



1000

1002

PLACING AN INTEGRATED CIRCUIT  
PACKAGE ON THE CIRCUIT BOARD

1004

PLACING A SLIGHTLY CURVED PRESSURE PLATE  
ON A TOP SURFACE OF THE INTEGRATED CIRCUIT PACKAGE

1006

PLACING A GASKET BETWEEN THE INTEGRATED  
CIRCUIT PACKAGE AND THE SLIGHTLY CURVED PRESSURE PLATE

1008

PLACING A SLIGHTLY CURVED BACKING PLATE  
ON A BOTTOM SURFACE OF THE CIRCUIT BOARD

1010

APPLYING FORCE TO THE OUTER EDGES OF THE PLATES TO  
RETAIN THE INTEGRATED CIRCUIT PACKAGE ON THE CIRCUIT  
BOARD AND TO CREATE AN EVENLY DISTRIBUTED PRESSURE  
ACROSS CONDUCTORS OF THE INTEGRATED CIRCUIT PACKAGE

1012

PLACING A HEAT SINK ON THE  
SLIGHTLY CURVED PRESSURE PLATE

1014

ATTACHING THE HEAT SINK TO THE CIRCUIT BOARD

FIG. 10